

TA1227AP

EDTV2 IDENTIFICATION CONTROL SIGNAL DETECTOR

The TA1227AP detects EDTV2 identification signals. It detects the 27 bits on the 22H and 285H lines of each frame and outputs to the read bus. The methods of detection are following.

B1 to B5, and B24 NRZ signal :

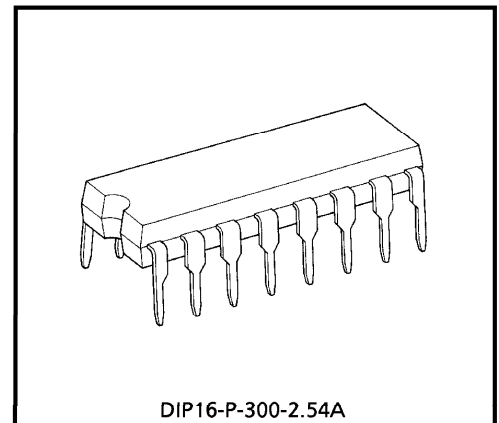
Y signal level detection

B25 to B27 (4/7) fsc :

Y signal level detection at BPF output

B6 to B23 fsc phase modulation signal :

Converts the IQ demodulation signal of the main signal processing IC to a color difference signal and detects the level

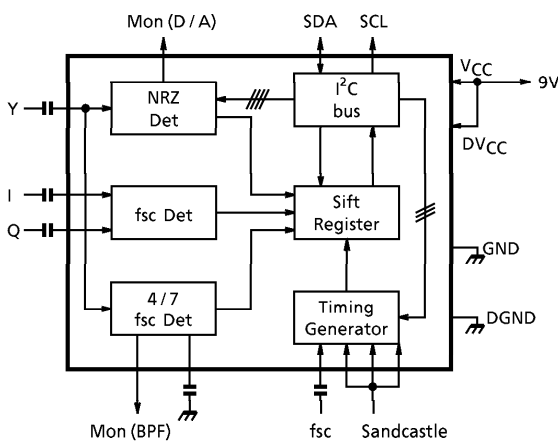


Weight : 1.11g (Typ.)

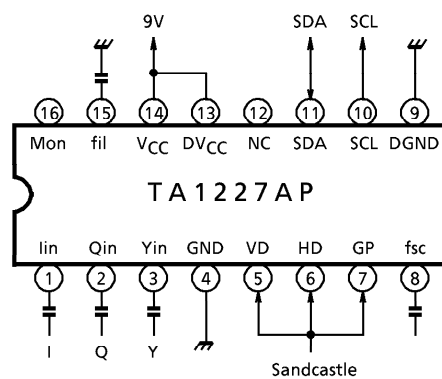
FEATURES

- I²C bus-controllable
- Y and I, Q inputs
- Compatible with sandcastle pulse (VD, HD, and GP) input
- Auto adjustment of 4/7 fsc BPF f₀

BLOCK DIAGRAM



PIN ASSIGNMENT DIAGRAM



All capacitors are 0.01 μF

TERMINAL FUNCTION

PIN No.	PIN NAME	FUNCTION	INTERFACE CIRCUIT
1	I input	I signal input terminal. Input the I signal to this terminal via a clamping capacitor (0.01 μ F recommended). The typical input level is 0.3V _{p-p} . This terminal is used to identify bits 6 to 23 of the identification signal. If no I signal is input, connect this terminal to the AC GND.	
2	Q input	Q signal input terminal. Input the Q signal to this terminal via a clamping capacitor (0.01 μ F recommended). The typical input level is 0.3V _{p-p} . This terminal is used to identify bits 6 to 23 of the identification signal. If no Q signal is input, connect this terminal to the AC GND.	
3	Y input	Y signal input terminal. Input the Y signal to this terminal via a clamping capacitor (0.01 μ F recommended). The typical input level is 1.0V _{p-p} . This terminal is used to identify bits 1 to 5 and 24 to 27 of the identification signal.	
4	GND	GND terminal for analog block	—
5	VD input	VD signal input terminal. Input a signal of positive polarity. The threshold level is 1.5V (typ.). The rising phase of the VD signal acts as the trigger to start the HD count and the 22H and 285H lines are identified. This terminal can also be used to input sandcastle pulses to which VD, HD, and GP are multiplexed.	

PIN No.	PIN NAME	FUNCTION	INTERFACE CIRCUIT
6	HD input	<p>HD signal input terminal. Input a signal of positive polarity with a width that can accommodate GP. The threshold level is 3.5V (typ.). Note that VD is canceled if HD rises within 1μs of VD rising. This terminal can also be used to input sandcastle pulses to which VD, HD, and GP are multiplexed.</p>	
7	GP input	<p>Gate pulse input terminal. Input a signal of positive polarity. The threshold level is 7.0V (typ.). The read timing for each 27 bits is determined from the rising phase of the GP signal. Note that Y and I, Q inputs are clamped while GP is high. This terminal can also be used to input sandcastle pulses to which VD, HD, and GP are multiplexed.</p>	
8	fsc input	<p>Terminal for input of 3.58MHz continuous signal for the IC's internal reference clock. Input a signal locked to the color subcarrier of the video signal to be demodulated. The typical input level is 0.6V_{p-p}.</p>	
9	D.GND	<p>GND pin for digital block</p>	<p style="text-align: center;">—</p>
10	SCL	<p>SCL input terminal for I²C bus. The threshold level is 2.5V.</p>	

PIN No.	PIN NAME	FUNCTION	INTERFACE CIRCUIT
11	SDA	SDA I/O terminal for I ² C bus. The threshold level is 2.5V. The current flowing through this terminal should not exceed 3.0mA.	
12	N.C.	This terminal is not connected and should be left open.	—
13	D.VCC	Power supply pin for the digital block. Apply 9.0V (typ.).	—
14	VCC	Power supply terminal for the analog block. Apply 9.0V (typ.).	—
15	f ₀ adjustment	Terminal for connecting f ₀ automatic adjustment filter of 4/7fsc BPF. The recommended capacitance is 0.01μF.	
16	Monitor output	Terminal for monitoring DAC output for NRZ-Compared level and 4/7fsc BPF output. Write Data D4 of the I ² C bus switches functions. When "0", the pin is set for DAC output : when "1", for monitoring BPF output.	

I²C BUS MAP

MODE	DATA							
	D7	D6	D5	D4	D3	D2	D1	D0
WRITE (Slave Address : BC HEX)	Timing (100)			Monitor (0)	NRZ-Det. level (1000)			
READ (Slave Address : BD HEX)	B1	B2	B3	B4	B5	B6	B7	B8
	B9	B10	B11	B12	B13	B14	B15	B16
	B17	B18	B19	B20	B21	B22	B23	B24
	B25	B26	B27	—	—	—	P.O.R.	Busy

() : Default values are shown in parenthesis.

I²C BUS CONTROL

Timing [sc]	
001	- 3
010	- 2
011	- 1
* 100	0
101	1
110	2
111	3

Monitor	
* 0	NRZ-Ref. level
1	BPF

NRZ-Det. level	[IRE]	[mV _{p-p}]
0000	10	71.4
0001	12	85.7
0010	14	100.0
0011	16	114.3
0100	18	128.6
0101	20	142.9
0110	22	157.1
0111	24	171.4
* 1000	26	185.7
1001	28	200.0
1010	30	214.3
1011	32	228.6
1100	34	242.9
1101	36	257.1
1110	38	271.4
1111	40	285.7

1sc = 280ns (1 / fsc)

* Default value

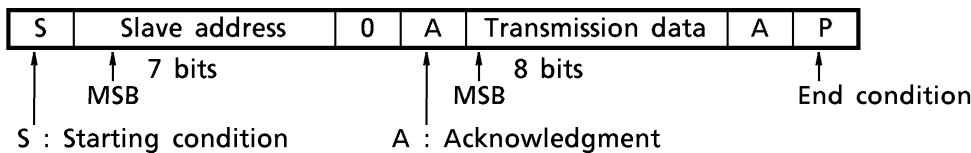
- Timing : The phase of the sampling pulse for reading each 27 bits of the identification signal can be adjusted by 7sc in 1sc steps. Don't use the data (000).
- Monitor : Switches the signal output from pin 16.
- NRZ-Det. level : Adjusts the NRZ detection level.
The det. level can be adjusted by 30IRE (=214mV) in 2IRE steps.
There are errors within a tolerance ±3IRE (= ±21.4mV) against upper values.
- P.O.R. (Power On Reset) : This bit shows that the bus data has been reset to the default value when the power is turned ON. After the POR, this bit is "1" for the first data output, then "0" for subsequent output. POR is applied at V_{CC}=6V (typ.).
- Busy : This bit is "1" while reading the 27 bits of the identification signal on the 22H and 285H lines, and "0" at other times.

I²C BUS TRANSMISSION AND RECEPTION METHODS

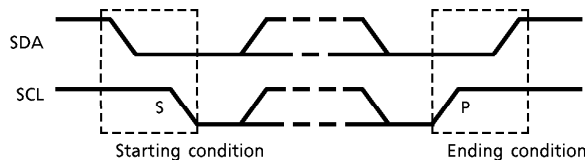
Slave address

A6	A5	A4	A3	A2	A1	A0	W/R
1	0	1	1	1	1	0	0/1

Data transmission format (Write mode)

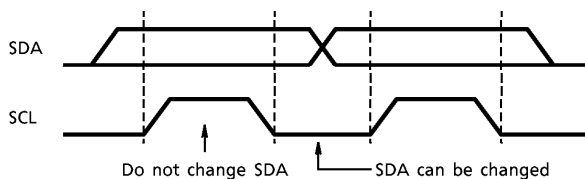


Starting and ending conditions

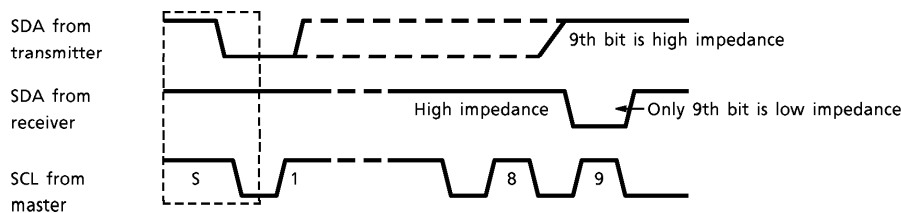


Purchase of TOSHIBA I²C components conveys a license under the philips I²C patent rights to use these components in an I²C system, provided that the system conforms to the I²C standard specification as defined by philips.

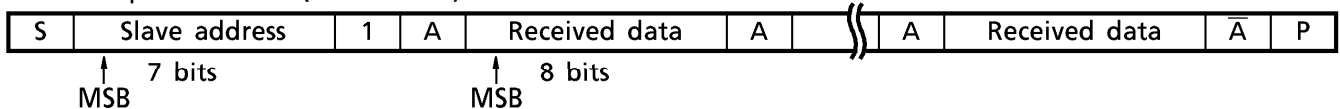
Bit transmission



Acknowledgment



Data reception format (Read mode)



When receiving data, the master transmitter changes to a receiver immediately after the first acknowledgment, while the slave receiver changes into the transmitter. The master always creates the end condition. Detailed specifications conform to the PHILIPS I²C Specification.

MAXIMUM RATINGS

CHARACTERISTIC	SYMBOL	RATING	UNIT
Power Supply Voltage	V_{CC}	14.0	V
Power Dissipation	P_D	1380 (Note)	mW
Operating Temperature	T_{opr}	-20~65	°C
Storage Temperature	T_{stg}	-55~150	°C

(Note) When using the device at above $T_a = 25^\circ\text{C}$, decrease the power dissipation by 11.2mW for each increase of 1°C .

RECOMMENDED OPERATING CONDITIONS

($V_{CC} = 9\text{V}$, $D.V_{CC} = 9\text{V}$, and $T_a = 25^\circ\text{C}$ unless otherwise specified)

PIN No.	CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	REMARKS
13	D.V _{CC}	D.V _{CC}	8.1	9.0	9.9	V	—
14	V _{CC}	V _{CC}	8.1	9.0	9.9	V	—
1	I Input Amplitude	lin	0.15	0.3	0.35	V _{p-p}	When ID signal demodulated
2	Q Input Amplitude	Qin	0.15	0.3	0.35	V _{p-p}	When ID signal demodulated
3	Y Input Amplitude	Yin	0.8	1.0	1.2	V _{p-p}	Amplitude between bottom of sync and 100% white
5	VD Input Voltage	VDin	1.8	—	9.0	V	Pulse high level
6	HD Input Voltage	HDin	3.8	—	9.0	V	Pulse high level
7	GP Input Voltage	GPin	7.3	—	9.0	V	Pulse high level
8	fsc Input Amplitude	fsc in	0.3	0.6	—	V _{p-p}	—
9	VD Rise Phase	t _{VD}	1085	—	1130	μs	The rising phase should be before the starting point in the 22 / 285H lines.
10	GP Rise Phase	t _{GP}	5.6	—	7.3	μs	After fall in H.sync (While adjusting from -3sc to +3sc)
11	GP Width	W _{GP}	1.0	—	—	μs	—

* HD must be input with a line blanking interval such that its width accommodates GP.

ELECTRICAL CHARACTERISTICS ($V_{CC} = 9.0V$, $D.V_{CC} = 9.0V$ and $T_a = 25^\circ C$ unless otherwise specified)

DC CHARACTERISTICS

Terminal voltages

PIN No.	CHARACTERISTIC	SYMBOL	TEST CIR-CUIT	MIN.	TYP.	MAX.	UNIT	REMARKS
1	I Input	V1	—	3.80	4.25	4.70	V	Pin 7 : greater than 7V
2	Q Input	V2	—	3.80	4.25	4.70	V	Pin 7 : greater than 7V
3	Y Input	V3	—	3.80	4.25	4.70	V	Pin 7 : greater than 7V
4	GND	—	—	—	0	—	V	—
8	fsc Input	V8	—	6.20	6.75	7.30	V	—
9	D.GND	—	—	—	0	—	V	—
13	D.V _{CC}	D.V _{CC}	—	—	9.0	—	V	—
14	V _{CC}	V _{CC}	—	—	9.0	—	V	—
15	f ₀ Auto Adjustment	V15	—	1.0	1.5	2.0	V	—
16	Monitor Output	V16		3.1	3.6	4.1	V	D/A output

Current consumption

PIN No.	CHARACTERISTIC	SYMBOL	TEST CIR-CUIT	MIN.	TYP.	MAX.	UNIT
13	D.V _{CC}	D.I _{CC}	—	23.0	30.0	37.0	mA
14	V _{CC}	I _{CC}	—	10.0	12.5	15.0	mA

AC CHARACTERISTICS

CHARACTERISTIC	SYMBOL	TEST CIR-CUIT	MIN.	TYP.	MAX.	UNIT	REMARKS
VD Threshold Level	V _{VDth}	—	1.3	1.5	1.7	V	Design value
HD Threshold Level	V _{HDth}	—	3.3	3.5	3.7	V	Design value
GP Threshold Level	V _{GPth}	—	6.8	7.0	7.2	V	Design value
NRZ Detection Errors	Δ NRZ	—	-3	0	+3	IRE	Against the level set by bus
		—	-21.4	0	+21.4	mV	
4 / 7fsc Detection Level	V _{47fsc}	—	—	118	150	mV _{p-p}	Design value, f = 2.04545MHz
BPF Attenuation	G ₁	—	20	—	—	dB	Design value, f = 1MHz
	G _{3.08}	—	20	25	—	dB	Design value, f = 3.08MHz
	G _{3.58}	—	30	35	—	dB	Design value, f = 3.579545MHz
	G _{4.5}	—	35	40	—	dB	Design value, f = 4.5MHz
BPF Group Delay	τ _{47fsc}	—	—	1.2	—	μ s	Design value, f = 2.04545MHz
Sampling Start Phase (Note)	t _{sp}	—	2.79	3.07	3.35	μ s	Design value, should be later than rise in GP.

(Note) Bus data : default

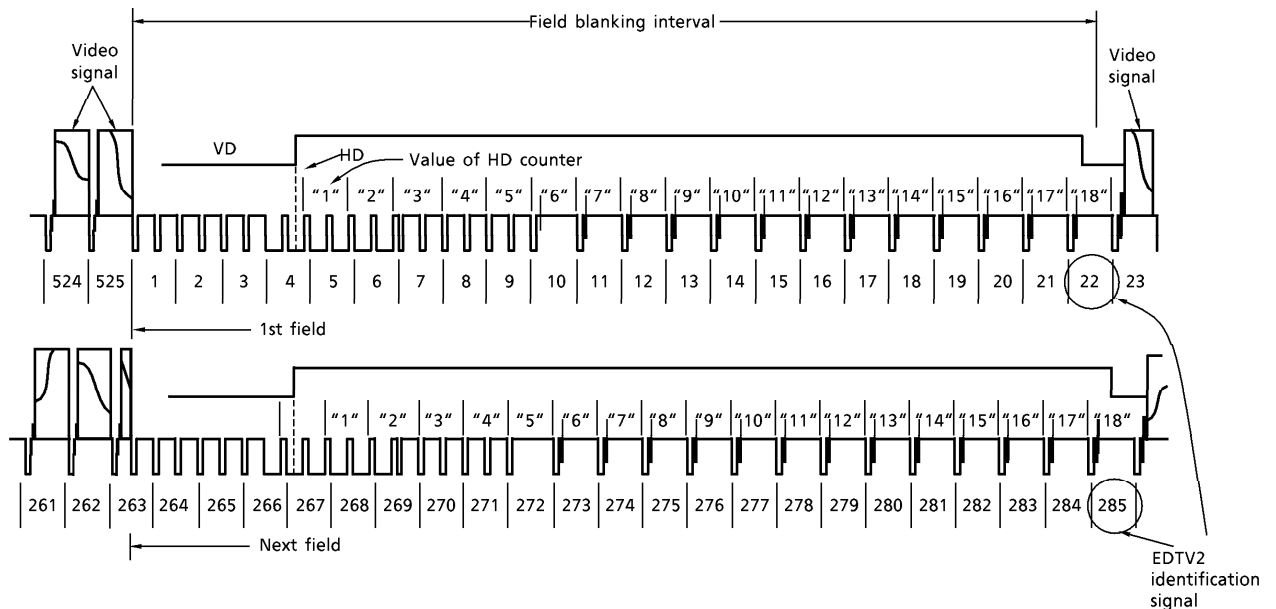
VD, HD, AND GP INPUT TIMING

In the TA1227AP, the rise in VD triggers the start of the HD count. A window is opened between the 17th and 18th fall in HD during which GP is sampled (see figure). The rise in the sampled GP is used as a reference for creating a sampling pulse for reading the bits of the EDTV2 identification signal. Therefore, it should be set so that VD rises during the 4H and 267H lines. The sampling pulse for the first bit rises 11sc after the rise in the reference gate pulse. The pulse width ratio is 3 : 4 (high : low). The sampling pulse phasing is under bus control (−3sc to +3sc).

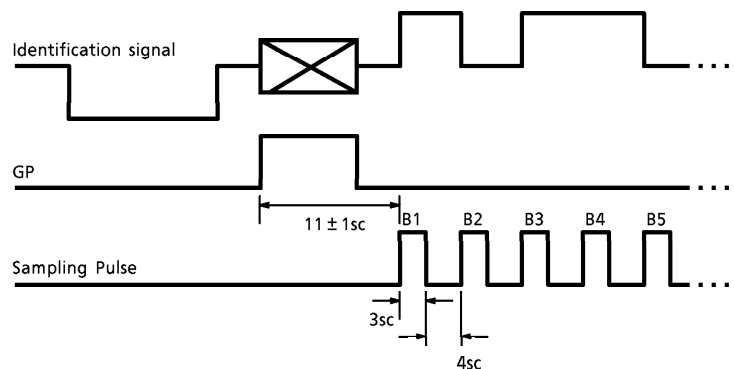
The threshold levels of the respective pulses are : VD : 1.5V, HD : 3.5V, and GP : 7.0V. Note that, if HD rises within 1μs of a rise in VD, that VD is canceled.

The TA1227AP will accept the input of sandcastle pulses to which VD, HD, and GP are multiplexed.

HD, VD TIMINGS

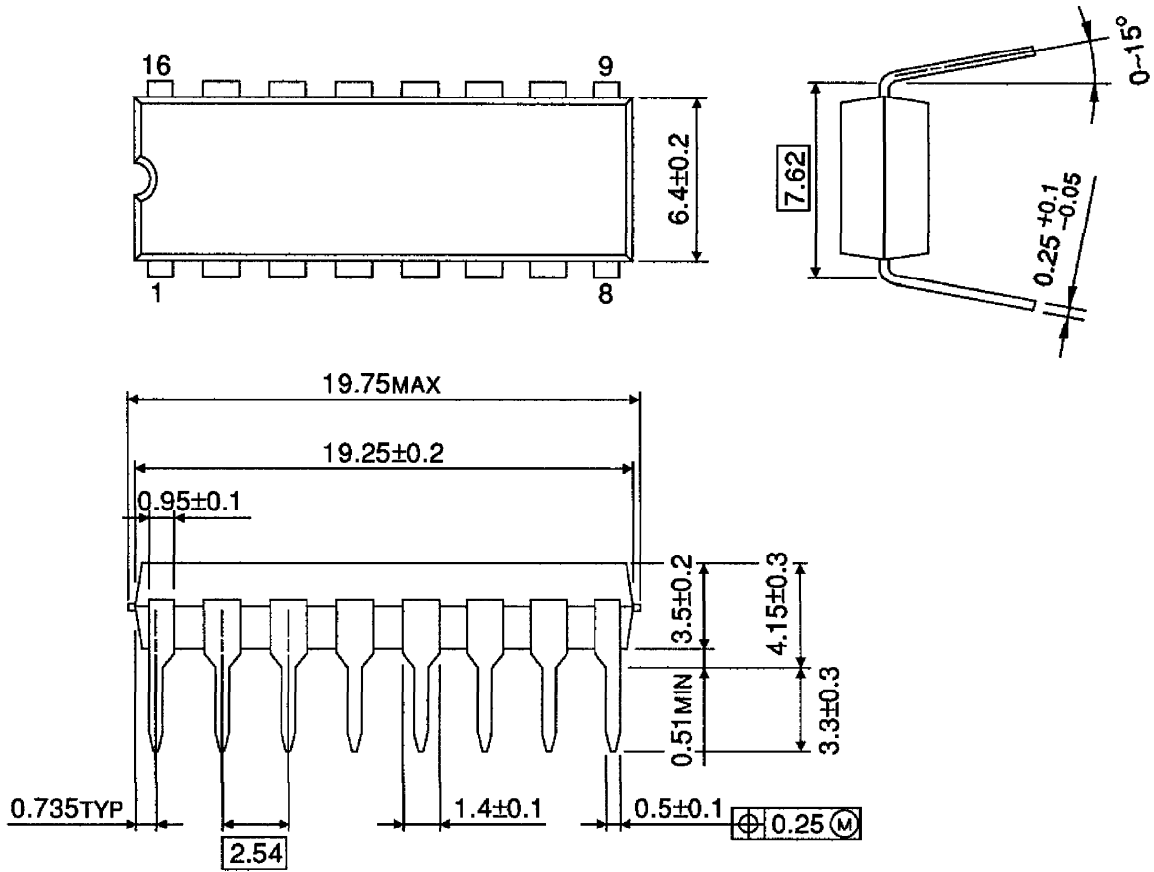


22 / 285H LINE



PACKAGE DIMENSIONS
DIP16-P-300-2.54A

Unit : mm



Weight : 1.11g (Typ.)

RESTRICTIONS ON PRODUCT USE

000707EBA

- TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property. In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc..
- The TOSHIBA products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.). These TOSHIBA products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation instruments, traffic signal instruments, combustion control instruments, medical instruments, all types of safety devices, etc.. Unintended Usage of TOSHIBA products listed in this document shall be made at the customer's own risk.
- The products described in this document are subject to the foreign exchange and foreign trade laws.
- The information contained herein is presented only as a guide for the applications of our products. No responsibility is assumed by TOSHIBA CORPORATION for any infringements of intellectual property or other rights of the third parties which may result from its use. No license is granted by implication or otherwise under any intellectual property or other rights of TOSHIBA CORPORATION or others.
- The information contained herein is subject to change without notice.